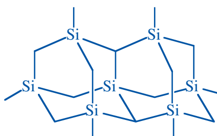
Volatile Carbosilanes

Volatile carbosilanes are the preeminent precursors for:

- Silicon Carbide films and buffer layers
- Carbon-doped (Tensile-Strained) Silicon
- ALD promoted patterning and seed layers
- SiCO:H films for low-k, barrier layers and etch-stop
- Silicon Carbonitride utilized in passivation of silicon-based photovoltaics

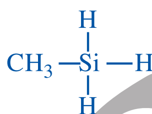
By appropriate selection of the carbosilane precursor and deposition conditions the silicon carbide framework can be shifted toward substituted silicon and diamond-like structures.



Carbosilanes are compounds in which the elements of silicon and carbon alternate in a molecular framework or polymeric backbone in an approximate ratio of 1:1 according to the following general structure:

Carbosilane Compounds

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIM6515.0				
METHYLSILANE	46.14	-57 (-157)	0.628 [-58]	
CH_6Si *1MS*				



CAUTION: CAN FORM EXPLOSIVE MIXTURES WITH AIR

ΔHcomb: -624 kcal/mole
ΔHform: -7 kcal/mole
ΔHvap: 4.6 kcal/mole
Vapor pressure, -80°: 241 mm
Vapor pressure, 21°: 14 atm (210 psia)

Flashpoint: <-40°C (<-40°F)
Autoignition temperature: 130°C
Critical temperature: 79.3°
Dipole moment: 0.73 debye

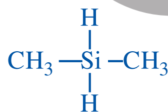
Plasma polymerization yields dry process photoresist.[1]
Intermediate for poly(methylsilane) precursor to silicon carbide.[2]
Deposits SiC on Si and Ge at 400 - 500°C.[3]
Source for hydrogenated amorphous silicon carbide films.[4]

1. Dabbagh, G. et al. *J. Photopolym. Sci. Tech.* **1998,** *11*, 651.
2. Fhang, Z. et al. *J. Am. Ceram. Soc.* **1991,** *74*, 670.
3. Takatsuka, T. et al. *Appl. Surf. Sci.* **2000,** *162*, 156.
4. Lee, M. et al. in "*Chemical Aspects of Electronic Ceramics Processing*" Arkles, B. ed., MRS Proc. **1998**, *495*, 153.

HYDROLYTIC SENSITIVITY: 9: reacts extremely rapidly with atmospheric moisture - may be pyrophoric - glove box or sealed system required

[992-94-9] TSCA EC 213-598-5 HMIS: 3-4-3-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SID4230.0				
DIMETHYLSILANE	60.17	-20 (-150)	0.68 [-20]	
C_2H_8Si				



ΔHcomb: -624 kcal/mole
ΔHform: -23 kcal/mole
ΔHvap: 5.5 kcal/mole

Flashpoint: <-40°C (<-40°F)
Vapor pressure, -80: 30 mm
Dipole moment: 0.75 debye

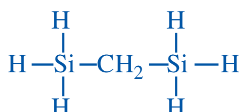
Generates cubic silicon carbide by plasma CVD.[1]
Epitaxial growth of cubic silicon carbide carried out by triode plasma CVD.[2]

1. Hashim, A. et al. *Semiconductor Electronics, IEE Int'l. Conf. Proc.* **2006**, 646.
2. Yasuiet, K. et al. *Appl. Surf. Sci.* **2000**, *159*, 556.

HYDROLYTIC SENSITIVITY: 3: reacts with aqueous base

[1111-74-6] TSCA EC 214-184-7 HMIS: 3-4-1-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SID4595.0				
1,3-DISILAPROPANE	76.24	14.7	0.697 [4]	1.4115 [4]
DISILMETHYLENE				
CH_8Si_2				



CAUTION: PYROPHORIC, FORMS EXPLOSIVE MIXTURES WITH AIR
AIR TRANSPORT FORBIDDEN

HYDROLYTIC SENSITIVITY: 9: reacts extremely rapidly with atmospheric moisture - may be pyrophoric - glove box or sealed system required

[1759-88-2] HMIS: 4-4-2-X

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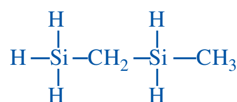
Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SID4592.0 1,3-DISILABUTANE	90.27	44-5	0.80	1.436 [25]



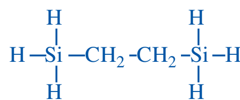
SID4592.0
1,3-DISILABUTANE
1-METHYLDISILMETHYLENE
$C_2H_{10}Si_2$

Precursor for low temperature CVD of silicon carbide MEMS.[1,2]

1. Stoldt, C. et al. *Sens.Actuators, A* **2002**, *97-8*, 410.
2. Stoldt, C. et al. *Appl. Phys. Lett.* **2001**, 347.

HYDROLYTIC SENSITIVITY: 3: reacts with aqueous base
[6787-86-6] HMIS: 3-4-2-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SID4593.0 1,4-DISILABUTANE	90.27	45-6 (-15)	0.697	1.4141



SID4593.0
1,4-DISILABUTANE
1,2-ETHANEDIYLBIS(SILANE)
$C_2H_{10}Si_2$
Flashpoint: -31°C (-24°F)
Autoignition temperature: 152°C

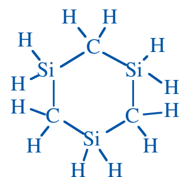
CAUTION: VAPORS HAVE BEEN REPORTED TO SPONTANEOUSLY IGNITE

Bonds to oxide-free titanium, gold and silicon substrates.[1]
Forms 0.2-1.7% carbon doped silicon films.[2]

1. Arkles, B. et al. *J. Adhes. Sci. Technol.* **2012**, *26*, 41.
2. Okada, L. et al. *Surf. Sci.* **1998**, *418*, 353.

HYDROLYTIC SENSITIVITY: 9: reacts extremely rapidly with atmospheric moisture - may be pyrophoric - glove box or sealed system required
[4364-07-2] HMIS: 2-4-2-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIT8709.3 1,3,5-TRISILACYCLOHEXANE	132.38	135 (-10)	0.9001	1.5059



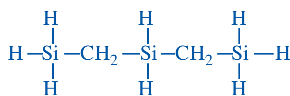
SIT8709.3
1,3,5-TRISILACYCLOHEXANE
CYCLOTRISILMETHYLENE
$C_3H_{12}Si_3$

Single source precursor for beta-SiC by LPCVD at 800-1,000°.[1]

1. Lienhard, M. et al. in "*Chemical Aspects of Electronic Ceramics Processing*" Arkles, B. ed., MRS Proc. **1998**, *495*, 139.

HYDROLYTIC SENSITIVITY: 3: reacts with aqueous base
[291-27-0] HMIS: 3-4-1-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIT8709.8 1,3,5-TRISILAPENTANE	120.37	100	0.7628	1.4491



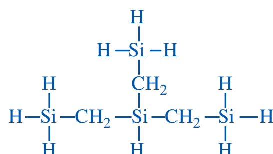
SIT8709.8
1,3,5-TRISILAPENTANE
BIS(SILYLMETHYL)SILANE
$C_2H_{12}Si_3$
Flashpoint: -16°C (3°F)

Employed in ALD of SiC films
Employed in PECVD of silicon carbide and silicon carbonitride "seed" layers.[1]

1. Weidman, T. et al. US Patent Appl. 2012/0122302 A1, 2012.

HYDROLYTIC SENSITIVITY: 7: reacts slowly with moisture/water
[5637-99-0] TSCA-L HMIS: 3-4-2-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIT8715.9 TRIS(SILYLMETHYL)SILANE	164.48	61-2 / 30	0.806	1.4669 [25]



SIT8715.9
TRIS(SILYLMETHYL)SILANE
$C_3H_{16}Si_4$
Flashpoint: 35°C (95°F)

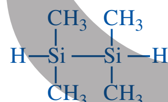
Employed in PECVD of silicon carbide and silicon carbonitride "seed" layers
HYDROLYTIC SENSITIVITY: 7: reacts slowly with moisture/water
[1385027-19-9] HMIS: 3-3-2-X

Oligosilanes and Polysilanes

Oligosilanes and polysilanes undergo conversion to Carbosilanes at temperatures above 650°.

$$H\!-\!\left(Si(CH_3)_2\right)_n\!-\!H \longrightarrow H\!-\!\left(SiH(CH_3)\!-\!CH_2\right)_n\!-\!H$$

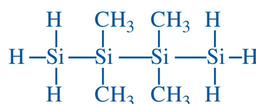
Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIT7541.0 1,1,2,2-TETRAMETHYLDISILANE	118.32	86-7 (-93)	0.720	1.429



SIT7541.0
1,1,2,2-TETRAMETHYLDISILANE
$C_4H_{14}Si_2$
Flashpoint: -26°C (-15°F)

HYDROLYTIC SENSITIVITY: 3: reacts with aqueous base
[814-98-2] TSCA HMIS: 2-4-1-X

Name	MW	bp °C/mm (mp)	D_4^{20}	n_D^{20}
SIT7580.0 2,2,3,3-TETRAMETHYLTETRASILANE, 95%	178.53	125-135		

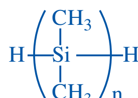


SIT7580.0
2,2,3,3-TETRAMETHYLTETRASILANE, 95%
$C_4H_{18}Si_4$

Candidate material for nanowires.[1]

1. Arkles, B. et al. U.S. Patent Appl. 20120076840, 2012.

HYDROLYTIC SENSITIVITY: 7: reacts slowly with moisture/water
[1364487-19-3] HMIS: 2-4-1-X



PSS-1M01
poly(DIMETHYLSILANE) MW 1000-3000

DP: 25-50 Flashpoint: 103° Tm: 250-270° (substantial degradation before mp)

Solid state source for volatile siliconcarbonitride (SiCN) precursors utilized in passivation of silicon-based photovoltaics
Employed in CVD of silicon carbonitride films.[1]

1. Scarlete, M.; et al; US Patent 7,396,563; 2008 (Label Licensed Gelest Product)
2. Yajima, S. et al. *J. Mater. Sci.* **1978**, *13*, 2569.

[30107-43-8] / [28883-63-8] TSCA

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